

CLAIMS

1. A ceramic substrate provided with a conductor layer on the surface of said ceramic substrate or inside said ceramic
5 substrate,
wherein: the ratio (t_2/t_1) of the average thickness of said conductor layer (t_2) to the average thickness of said ceramic substrate (t_1) is less than 0.1; and a dispersion of the thickness of the conductor layer to the average thickness of the conductor
10 layer is in a range of -70 to +150%.
2. The ceramic substrate according to claim 1,
wherein said ceramic substrate is in a disc-shape with a diameter exceeding 150 mm.
15
3. The ceramic substrate according to claim 1 or 2,
wherein the thickness of said ceramic substrate is 25 mm or less.
- 20 4. The ceramic substrate according to any of claims 1 to 3,
wherein said conductor layer is an electrostatic electrode.
5. The ceramic substrate according to any of claims 1 to 3,
25 wherein said conductor layer is a resistance heating element.
6. The ceramic substrate according to any of claims 1 to 3,
wherein said conductor layer is any of a chuck top electrode,
30 a guard electrode and a ground electrode.